

UNIVERSITI TUN HUSSEIN ONN MALAYSIA

FINAL EXAMINATION SEMESTER II SESSION 2021/2022

COURSE NAME

: MANUFACTURING PROCESS

COURSE CODE

BPC 22203

PROGRAMME CODE :

BPB

EXAMINATION DATE:

JULY 2022

DURATION

: 3 HOURS

INSTRUCTIONS

1. ANSWER ALL QUESTIONS.

2. THIS FINAL EXAMINATION IS CONDUCTED VIA **CLOSED BOOK**.

3. STUDENTS ARE **PROHIBITED** TO CONSULT THEIR OWN MATERIAL OR EXTERNAL RESOURCES DURING THE EXAMINATION CONDUCTED VIA

CLOSED BOOK.

THIS QUESTION PAPER CONSISTS OF THREE (3) PAGES

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- Q1 (a) Illustrate the following metal forming processes with appropriate explanation.
 - (i) Flashless die forging

(5 marks)

(ii) Roll bending

(5 marks)

(b) Explain TWO (2) limitations of impression die forging.

(4 marks)

(c) A 350 mm-wide strip 32 mm thick is fed through a rolling mill with two powered rolls with radius of 275 mm. The work thickness is to be reduced to 22.5 mm in one pass at a roll speed of 60 rev/min and average flow stress of 420 MPa.

Calculate the roll force.

(6 marks)

Q2 LTC Electronic Sdn Bhd is a manufacturing subcontractor company specializing in printed circuit board manufacturing assembly and testing. One of the most critical equipment in the factory is Wave Soldering Machine. As illustrated in **Figure Q2**, wave soldering fundamental process includes solder flux spraying and molten solder deliver up through a narrow slot onto the underside of a printed circuit board to connect the component lead wires and form solder joints.

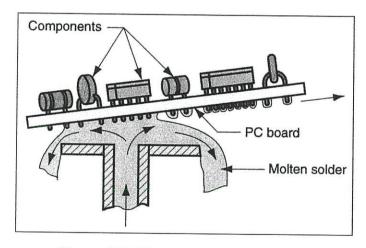


Figure Q2: Wave Soldering Machine

(a) Explain THREE (3) main purposes of soldering fluxes.

(9 marks)

(b) Discuss **TWO** (2) advantages of wave soldering process compared to hand soldering method.

(6 marks)

(c) Explain TWO (2) typical solder joint defects related to wave soldering process.

(5 marks)

Q3	(a)	Illustrate the following machining processes.			
		(i)	Contour turning	(2 1)	
		(**)		(3 marks)	
		(ii)	Chamfering	(3 marks)	
		(iii)	Counterboring	,	
		,		(3 marks)	
	(b)	Explain the function of the following lathe machine components.			
		(;)	Carrier		
		(i)	Carrier	(2 marks)	
		(ii)	Ways		
				(2 marks)	
		(iii)	Tailstock	(2	
				(2 marks)	
Q4	(a)	Differe	entiate between electric furnace and atmospheric control furnaces.		
				(5 marks)	
	(b)	Explai	n THREE (3) purposes of heat treatment.	(6 marks)	
	(c)	Explai	n electroplating with appropriate illustration.	()	
		1	Table of the second of the sec	(5 marks)	
	(d)	List F	OUR (4) surface texture elements.		
				(4 marks)	
Q5	(a)	Explain	n the working principle of 3D printing with appropriate illustration.		
				(8 marks)	
	(b)	Explain	n THREE (3) limitations of computer numerical control (CNC) mac	100	
	(a)	Ermlois		(6 marks)	
	(c)	Explaii	n THREE (3) applications of nanotechnology.	(6 marks)	
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